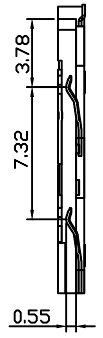
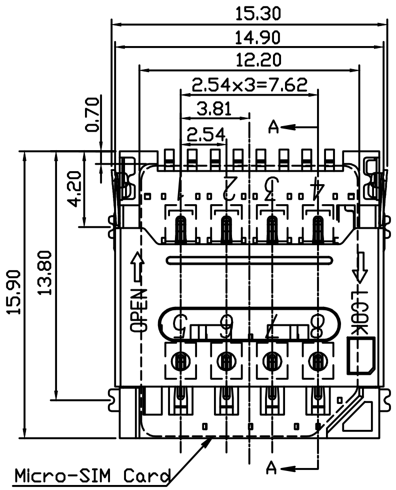
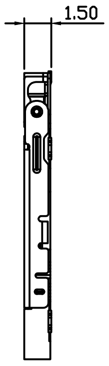
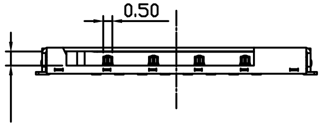
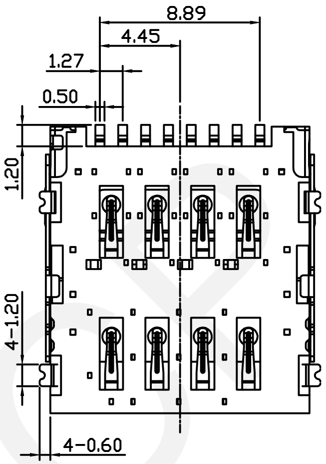


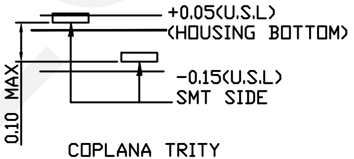
SECTION:A-A



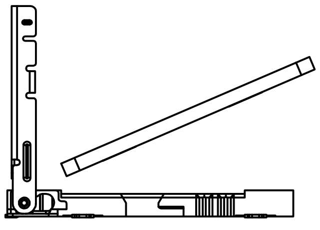




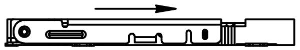




COPLANA TRITY

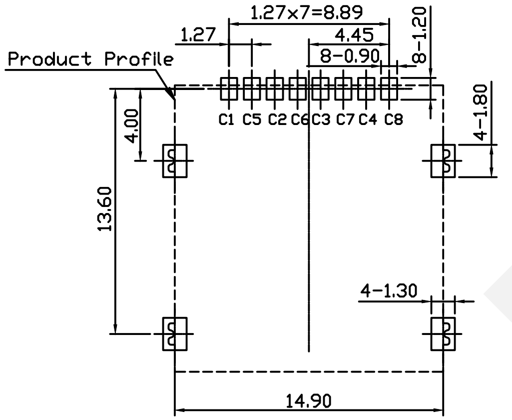


STEP 1 INSERT MICRO-SIM CARD



STEP 2 PUSH THE SHELL

STEP 3 FINISH



RECOMMENDED PCB LAYOUT

COMPONENT SIDE(TOLERANCE:±0.05)

| SIM Card | |
|---|---|
| Pin No. | Name |
| C1 | VCC |
| C2 | RST |
| C3 | CLK |
| C4 | Reserved |
| C5 | GND |
| C6 | VPP |
| C7 | I/O |
| C8 | Reserved |

Material

Housing:Thermoplastic,UL94V-0.

Terminal:Phosphor Bronze, T=0.15,Ni Plated Under,Au Plated On Contact Area,
G/F Plated On Soldertail.

Shell:Stainless Steel, T=0.15,Ni Plated Under,G/F Plated On Soldertail.

Electrical

Contact Resistance:60mΩ Max.

Insulation Resistance:1000MΩ Min.

Dielectric Withstanding Voltage:500V AC For 1 Minute.

Operation Temperature Range:-25°C TO+70°C

Durability:5000 Cycles.

RHTECP® NINGBO RHT ELECTRONIC CO.,LTD

| UNITS:mm | SHEET SIZE: A4 | SCALE:--- | |
|---|---|---|---|
| 0~3 | 3~18 | 18~50 | 50~120 |
| ±0.12 | ±0.15 | ±0.3 | ±0.5 |

DRWN BY PAN

CHK'D BY FENG

APPR BY ZHAN

Micro SIM CONN,HINGED TYPE:8Pin H1.5mm

THIRD ANGLE PROJECTION

RHTAYIM-089-8P-H1.5-R